


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE																																																																																																																					
<div>Application Number: 09/912844</div> <div>Confirmation Number: 5915</div> <div>First Named Applicant: Thomas Haverstock</div> <div>Attorney Docket Number:</div> <div>Search string: (6521466 or 6541278 or 6546946 or 6550484 or 6558475 or 6561213 or 6561220 or 6561481 or 6561767 or 6564826 or 5217043 or 20020001929).pn.</div> <div></div> <div><h3>US Patent Documents</h3><p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p><table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td>N</td><td>1</td><td>6521466</td><td>2002-02-18</td><td>Castrucci</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>2</td><td>6541278</td><td>2003-04-01</td><td>Morita et al.</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>3</td><td>6546946</td><td>2003-04-15</td><td>Dunmire</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>4</td><td>6550484</td><td>2003-04-22</td><td>Gopinath et al.</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>5</td><td>6558475</td><td>2003-05-06</td><td>Jur et al.</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>6</td><td>6561213</td><td>2003-05-13</td><td>Wang et al.</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>7</td><td>6561220</td><td>2003-05-13</td><td>McCullough et al.</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>8</td><td>6561481</td><td>2003-05-13</td><td>Filonczuk</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>9</td><td>6561767</td><td>2003-05-13</td><td>Biberger et al.</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>10</td><td>6564826</td><td>2003-05-20</td><td>Shen</td><td>B1</td><td></td><td></td></tr><tr><td>N</td><td>11</td><td>5217043</td><td>1993-06-08</td><td>Novakovi</td><td></td><td></td><td></td></tr></tbody></table><div><h3>US Published Applications</h3><p>Note: Applicant is not required to submit a paper copy of cited US Published Applications</p><table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Pub. No.</th><th>Date</th><th>Applicant</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td>N</td><td>1</td><td>20020001929</td><td>2002-01-03</td><td>Biberger et al.</td><td>A1</td><td></td><td></td></tr></tbody></table></div></div>							init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	N	1	6521466	2002-02-18	Castrucci	B1			N	2	6541278	2003-04-01	Morita et al.	B1			N	3	6546946	2003-04-15	Dunmire	B1			N	4	6550484	2003-04-22	Gopinath et al.	B1			N	5	6558475	2003-05-06	Jur et al.	B1			N	6	6561213	2003-05-13	Wang et al.	B1			N	7	6561220	2003-05-13	McCullough et al.	B1			N	8	6561481	2003-05-13	Filonczuk	B1			N	9	6561767	2003-05-13	Biberger et al.	B1			N	10	6564826	2003-05-20	Shen	B1			N	11	5217043	1993-06-08	Novakovi				init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass	N	1	20020001929	2002-01-03	Biberger et al.	A1		
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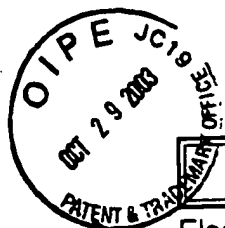
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Ram Karkar	11-26-03



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20	6164297	2000-12-26	Kamikawa	
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(Modified)

OCT 31 2003

U.S. Department of Commerce
Patent and Trademark Office

Attorney Docket No.: SSI-00501

Serial No.: 09/912,844

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(Use Several Sheets If Necessary)

Applicants: Maximilian A. Biberger et al.

(37 CFR § 1.98(b))

Filing Date: July 24, 2001

Group Art Unit: 1763

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2	AA	CN 1399790 A	02/26/03	China	H01L	21/00		X
2	AB	DE 36 08 783 A1	09/17/87	Germany	C30B	25/12		X
2	AC	DE 198 60 084 A1	07/06/00	Germany	H01L	21/3213		X
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Examiner: *Re*

Date Considered:

11-26-03

EXAMINER:

Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-1449
(Modified)U.S. Department of Commerce
Patent and Trademark Office

Attorney Docket No.: SSI-00501

Serial No.: 09/912,844

INFORMATION DISCLOSURE STATEMENT BY APPLICANT
(Use Separate Sheets If Necessary)

Applicants: Maximilian A. Biberger et al.

Filing Date: July 24, 2001

Group Art Unit: 1763

(37 CFR § 1.98(b))

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							Yes	No
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Examiner:

Date Considered:

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8

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Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE						
Application Number:	09/912844	*09/912844*					
Confirmation Number:	5915						
First Named Applicant:	Maximilian Sibenberger						
Attorney Docket Number:							
Search string:	(2617719 or 2625886 or 3744660 or 3968885 or 4029517 or 4091643 or 4245154 or 4341592 or 4355937 or 4367140 or 4406596 or 4422651 or 4474199 or 4522788 or 4549467 or 4592306 or 4601181 or 4626509 or 4670126 or 4682937 or 4693777 or 4749440 or 4778356 or 4789077 or 4823976 or 4825808 or 4827867 or 4838476 or 4865061 or 4879431 or 4917556 or 4924892 or 4951601 or 4960140 or 4983223 or 5011542 or 5044871 or 5062770 or 5071485 or 5105556 or 5167716 or 5169296 or 5169408 or 5186718 or 5188515 or 5190373 or 5191993).pn.						
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
Inh	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal. The current electronic filing contains part 1 out of a total of 4 electronic filings.

Signature

Examiner Name	Date
<i>R</i>	11-26-03

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8

Stylesheet Version v1.8.0

Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE						
Application Number:	09/912844	*09/912844*					
Confirmation Number:	5915						
First Named Applicant:	Maximilian Biberger						
Attorney Docket Number:							
Search string:	(5193560 or 5195878 or 5213485 or 5221019 or 5222876 or 5224504 or 5236669 or 5240390 or 5243821 or 5246500 or 5251776 or 5280693 or 5285352 or 5288333 or 5339844 or 5370741 or 5412958 or 5433334 or 5447294 or 5503176 or 5505219 or 5509431 or 5571330 or 5589224 or 5621982 or 5629918 or 5644855 or 5649809 or 5656097 or 5669251 or 5702228 or 5706319 or 5746008),pn.						
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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Remarks

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE						
Application Number:	09/912844	*09/912844*					
Confirmation Number:	5915						
First Named Applicant:	Maximilian Biberger						
Attorney Docket Number:							
Search string:	(5900107 or 5904737 or 5932100 or 5934991 or 5981399 or 5989342 or 6005226 or 6017820 or 6029171 or 6037277 or 6053348 or 6056008 or 6077053 or 6082150 or 6085935 or 6097015 or 6128830 or 6145519 or 6159295 or 6164297 or 6203582 or 6216364 or 6239038 or 6241825 or 6251250 or 6277753 or 6286231 or 6305677 or 6334266 or 6344174 or 6388317 or 6389677 or 6418956 or 6436824 or 6454945 or 6464790).pn.						
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8

Stylesheet Version v1.8.0

Title of
Invention**HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR
SUBSTRATE**

Application Number: 09/912844 *09/912844*
Confirmation Number: 5915
First Named Applicant: Thomas Haverstock
Attorney Docket Number:
Search string: (6521466 or 6541278 or 6546946 or 6550484 or 6558475 or
6561213 or 6561220 or 6561481 or 6561767 or 6564826 or
5217043 or 20020001929),pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Ink	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

Ink	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
2	1	20020001929	2002-01-03	Biberger et al.	A1		

Remarks

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